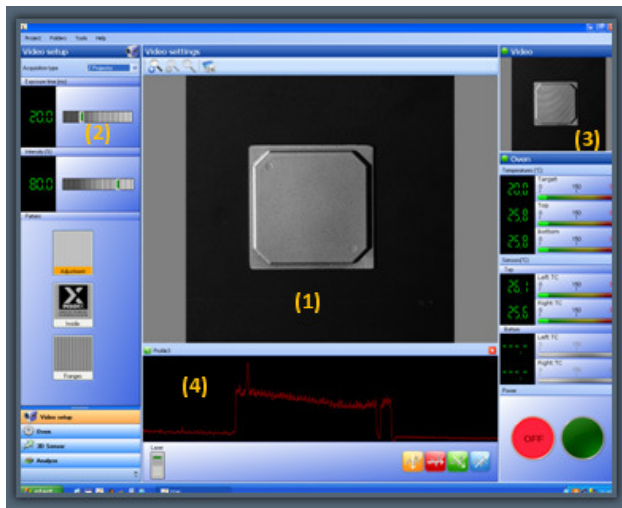


TDM

TOPOGRAPHY AND DEFORMATION MEASUREMENT

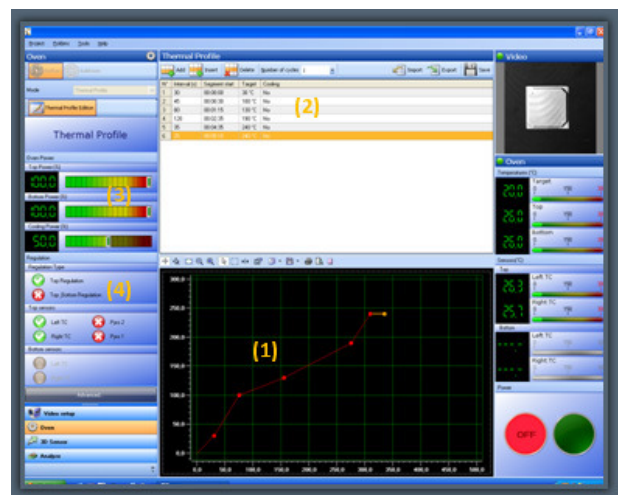
Each TDM system comes with our TDM-Control software. This modular software adapts to each specific system set-up, including eventually integrated hardware options as for example the sub room-temperature cycling capability.

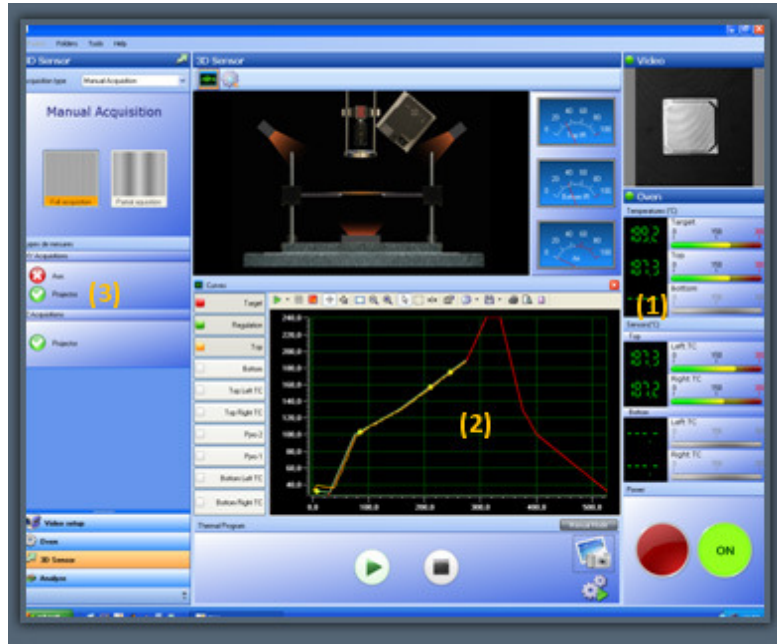
- *Optical and thermal set-up, data acquisition, and warpage analysis integrated in one single comprehensive software*
- *Extensive graphics support for great ease of use*
- *Customized multi-language support*



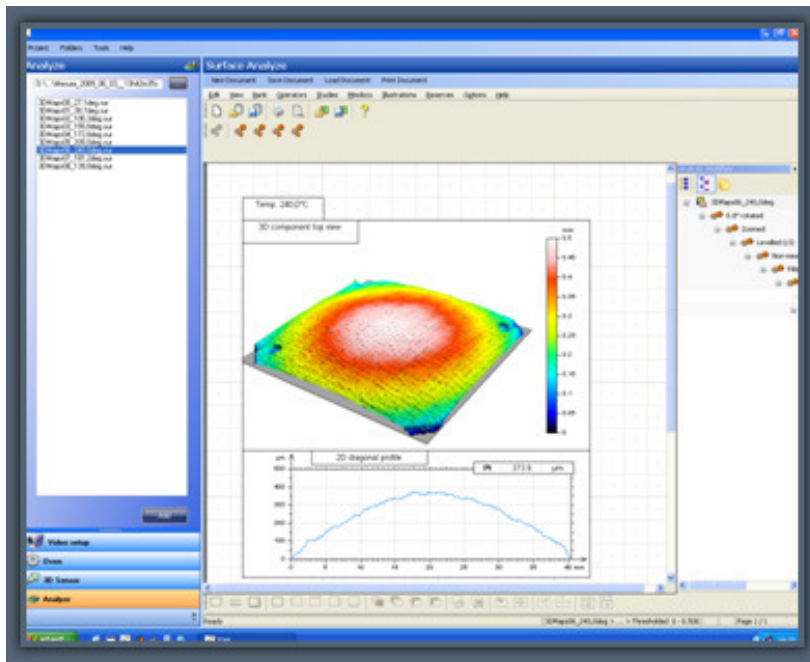
Adjustments like positioning the sample in the measurement volume (1) or correctly setting the exposure time (2) for a given sample reflectivity are made easy by permanent on-line monitoring of the CCD camera image (3) and the CCD camera saturation (4).

Graphical (1) and text (2) support makes the definition of the thermal profile fast and intuitive. The overall top and bottom heating power as well as the cooling power can be limited individually (3), in order to avoid overheating of small fragile samples. Each thermocouple can be enabled or disabled individually, for either top or bottom temperature measurement, or both (4), resulting in unprecedented flexibility in thermal control.





During the temperature progression, all relevant temperatures are permanently monitored and indicated **(1)**, and a customized selection of temperatures is graphically displayed **(2)** for maximum process control. Warpage acquisitions done during the temperature profile are indicated in the graph by markers **(2)**. It is the operators' choice to acquire the out-of-plane warpage, the in-plane deformation, or both simultaneously **(3)**.



Warpage analysis on the entire sample, on one sample out of a multiplicity of simultaneously analyzed samples, or on an operator defined fraction of a sample surface is integral part of the software. The possibility of defining macros for typical, repetitive analysis tasks greatly simplifies the everyday work.

